AMENDMENTS TO THE SPECIFICATION

At page 2, line 28 to end of page, please change the paragraph to read:

Such object is substantially achieved through the tool for handling wafers having the features set out in claim 1. of the present invention.

According to a further aspect, the present invention relates also to a station for epitaxial growth treatments, having the features set out in independent claim 9, wherein such tool finds an advantageous application.

At page 9, line 21-24, please change the paragraph to read:

In this case, if variable suction is desired, suction system 3 may advantageously comprise a Mass Flow Controller [MFC] <u>99</u> programmable, for example, by a computer sending "set points"; such controller controls the flow of inert gas and, as a consequence, the generated pressure depression.

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